

AMENDMENTS TO THE ABSTRACT

Please replace the abstract with the following amended abstract:

A method for fabricating a substrate, which includes a plurality of chip package substrates. One combined PCB includes a multi-layer rigid PCB and a flexible PCB. The multi-layer rigid PCB is fixed on the flexible PCB. At least one pair of grooves is formed on an upper surface of the multi-layer rigid PCB. A portion of the multi-layer rigid PCB between the grooves is milled to expose a corresponding portion of the flexible PCB to define an exposed area. The combined PCB is drilled through along two opposite sides of the grooves and the corresponding exposed area of the flexible PCB. Breakable parts are formed at a center of the corresponding portion of the flexible PCB and two opposite outside edges of the grooves.